

METHOD FOR ISOLATING SELF-ALIGNED CONTACT PADS

ABSTRACT OF THE DISCLOSURE

A method for isolating SAC pads of a semiconductor device, including
5 determining a chemical mechanical polishing process time necessary to isolate
the SAC pads a desired amount by referring to a relationship equation between
the extent of isolation of the self-aligned contact pads and the
chemical-mechanical polishing process time. The chemical mechanical
polishing process is performed for the determined process time on the
10 semiconductor device to isolate the self-aligned contact pads the desired amount.
The relationship equation is determined using a test semiconductor device.